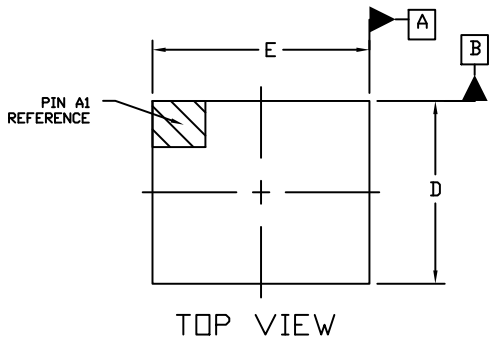




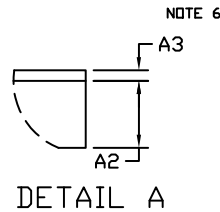
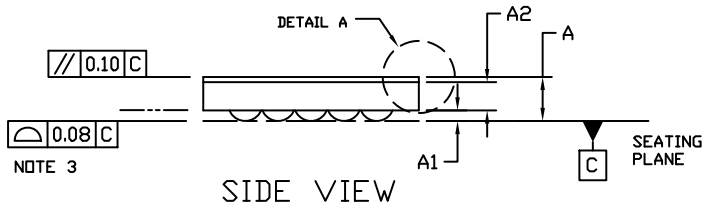
**WLCSP8 1.39x1.65x0.40**  
**CASE 567WK**  
**ISSUE B**

DATE 29 AUG 2018

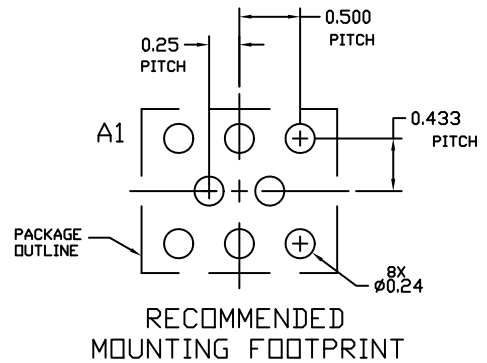
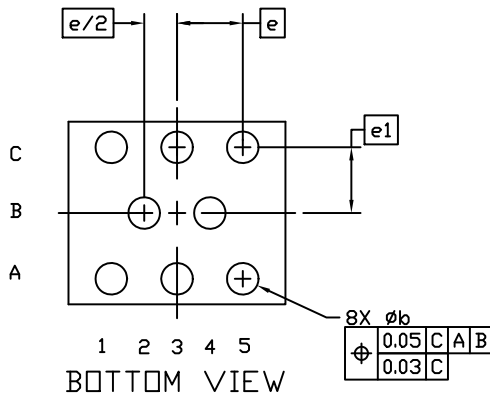


NOTES:

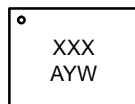
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION *b* IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
6. BACKSIDE COATING IS OPTIONAL.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	0.40
A1	0.06	0.08	0.10
A2	0.270 REF		
A3	0.025 REF		
<i>b</i>	0.22	0.24	0.26
D	1.29	1.39	1.49
E	1.55	1.65	1.75
<i>e</i>	0.500 BSC		
<i>e1</i>	0.433 BSC		



**GENERIC MARKING DIAGRAM\***



- XXX = Specific Device Code
- A = Assembly Location
- Y = Year
- W = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>WLCSP8 1.39x1.65x0.40</b>	<b>PAGE 1 OF 1</b>

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